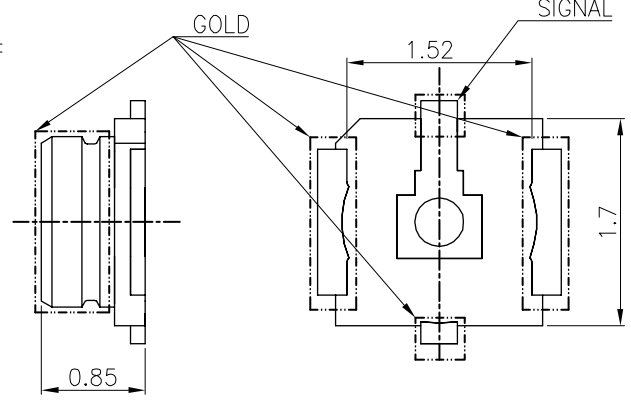
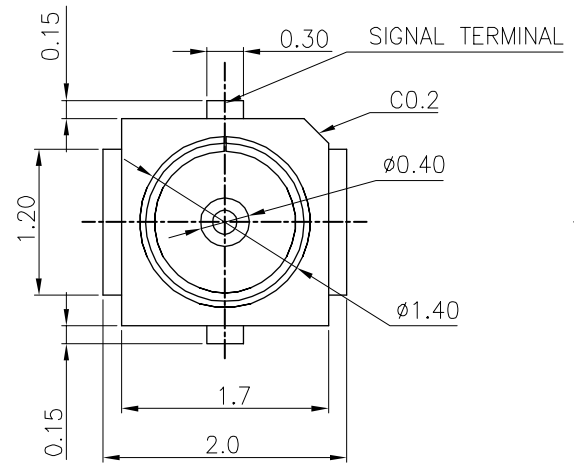
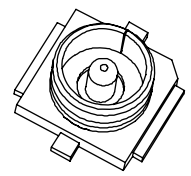
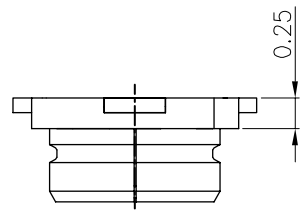


1 2 3 4 5 6 7 8

DCC ISSUE	Speedtech 2013.03.06 DCC發行		REV	MODIFICATION	DATE	DRAW	APPROVE
	F	EN1301043	22-JAN-13	AILIE	Y.J.		
	G	EN1301055	05-FEB-13	Jason	Y.J.		
	H	EN1302039	19-FEB-13	Jason	Y.J.		

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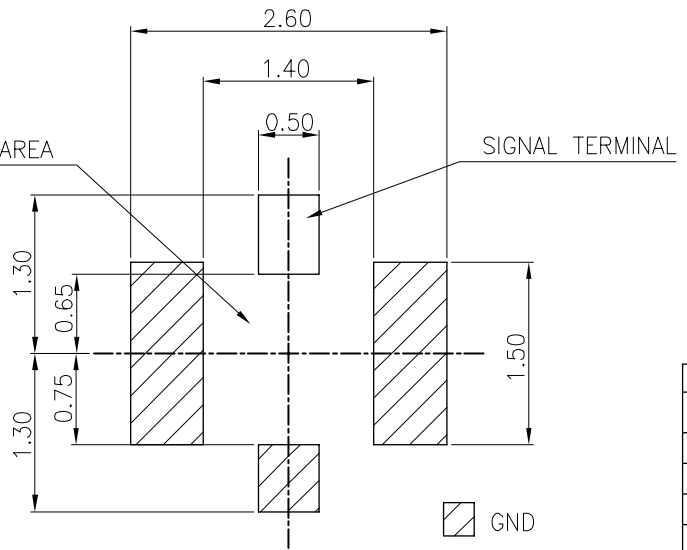
NOTES:

- MATERIAL:  
HOUSING: LCP, COLOR IN BLACK, UL94V-0 RATED.  
SIGNAL CONTACT: HIGH PERFORMANCE COPPER ALLOY.  
GROUND CONTACT: HIGH PERFORMANCE COPPER ALLOY.
- FINISH:  
SIGNAL CONTACT:  
50u" MIN. NICKEL UNDERPLATING ALL OVER.  
GOLD PLATING SEE ORDER INFORMATION.  
GROUND CONTACT:  
50u" MIN. NICKEL UNDERPLATING ALL OVER.  
GOLD PLATING SEE ORDER INFORMATION.
- COPLANARITY: 0.1mm MAX.
- HALOGEN FREE P/N:  
C89P104-0100XAH

CONTACT PLATING

- SIGNAL: GOLD FLASH. PLATING ALL OVER.  
GROUND: GOLD FLASH PLATING ALL OVER.
- SIGNAL: GOLD FLASH. PLATING ALL OVER.  
GROUND: GOLD FLASH PLATING ON SOLDER TAIL.
- SIGNAL: GOLD 1u" MIN. PLATING ALL OVER.  
GROUND: AG 100u" PLATING ALL OVER.

NO CONDUCTIVE TRACES IN THIS AREA



RECOMMENDED PCB MOUNTING PATTERN

DIMENSION IN mm [Inch]		PROD. SPEC.			
TOLERANCE UNLESS OTHERWISE SPECIFIED				Speedtech Corp.	
.X ± 0.20	X.* ±	PKG. SPEC.	FILE NO.	DWG NO.	
.XX ± 0.15	.X.* ±				C89-104-4
.XXX ± 0.10	.XX.* ±				
TITLE MICRO CONNECTOR RECEPTACLE CONTACT				CUSTOMER DRAWING	
APPROVE	CHECK	DRAW	PROJ.	SHEET	1 / 1
Y.J.	TC	KEN	SCALE 16:1	SIZE A4	REV H

1 2 3 4 5 6 7 8 8F-04-R11 REV:3

单击下面可查看定价，库存，交付和生命周期等信息

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